

L Number	Hits	Search Text	DB	Time stamp
7	637	((356/237.4,237.5,237.3).CCLS.) ((250/559.41,559.45).CCLS.) ((348/126).CCLS.) and ((wafer semiconductor) same (defect inspect\$))	USPAT; US-PGPUB	2004/02/27 18:52
8	161	((356/237.4,237.5,237.3).CCLS.) ((250/559.41,559.45).CCLS.) ((348/126).CCLS.) and ((wafer semiconductor) same (defect inspect\$))) and ("2003" "2004")	USPAT; US-PGPUB	2004/02/27 19:28
9	12	("5274434" "5486919" "5631733" "5748305" "5798831" "5856868" "5864394" "5883710" "5889593" "5903378" "5940175" "6256093").PN.	USPAT	2004/02/27 19:17
10	14	("4422755" "4540278" "4772126" "4895446" "4898471" "4966457" "5046847" "5355212" "5625193" "5659390" "5877507" "6201601" "6271916" "6288780").PN.	USPAT	2004/02/27 19:24
11	221	danko.in.	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:28
12	8	danko.in. and (wafer semiconductor\$ defect\$)	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:33
13	7556	(g01n021/00).ipc.	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:33
14	1884	(g01n021/86).ipc.	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:33
15	428	(g01v008/00).ipc.	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:34
16	42945	(h04n007/18).ipc.	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:34
17	711	(h04n009/47).ipc.	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:34
18	129	((g01n021/00).ipc.) and ((semiconductor\$ wafer) near (inspect\$ defect\$))	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:35
21	36	((h04n007/18).ipc.) and ((semiconductor\$ wafer) near (inspect\$ defect\$))	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:36
22	3	((h04n009/47).ipc.) and ((semiconductor\$ wafer) near (inspect\$ defect\$))	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:36
20	4	((g01v008/00).ipc.) and ((semiconductor\$ wafer) near (inspect\$ defect\$))	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:36
19	27	((g01n021/86).ipc.) and ((semiconductor\$ wafer) near (inspect\$ defect\$))	EPO; JPO; DERWENT; IBM_TDB	2004/02/27 19:36